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covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber; filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die.

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10. (Amended) A method of forming an integrated circuit package comprising:
 - attaching an interposer to a package substrate;
 - attaching an integrated circuit die to the interposer;
 - covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;
 - filling the internal chamber with a cooling fluid by pumping cooling fluid through a via in the package substrate and sealing the via after the internal chamber is filled.
11. (Amended) A method of forming an integrated circuit package comprising:
 - attaching an interposer to a package substrate;
 - attaching an integrated circuit die to the interposer;
 - covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;
 - filling the internal chamber with a cooling fluid by pumping cooling fluid through an inlet and sealing closed the inlet when the filling is complete.

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27. (Amended) An integrated circuit package comprising:
an integrated circuit die housed within a chamber, wherein the
integrated circuit die includes an active region;
a cooling fluid filling the chamber and in contact with the active
region of the integrated circuit die.